

No fee is believed to be due for this submission. Should any fees be required, however, please charge such fees to Deposit Account No. 16-1150.

Respectfully submitted,

Date: October 16, 2002



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Enclosures

Appendix A

Application No.: 09/869,660

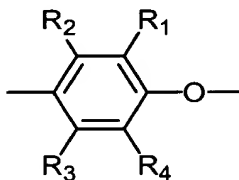
Attorney Docket No.: 7419-028



Marked up Version of The Amendments to The Claims

(with insertion and deletion indicated in bold-face underlining and brackets respectively)

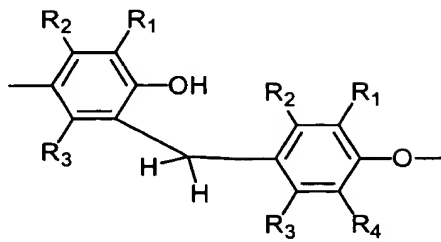
1. (Amended) A modified polyphenylene ether resin which is a reaction product of 100 parts by weight of (A) a polyphenylene ether having a main chain structure of the following formula (1):



(1)

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(wherein R₁ and R₄ each independently represents hydrogen, a primary or secondary lower alkyl, a phenyl, an aminoalkyl or a hydrocarboxy, and R₂ and R₃ each independently represents hydrogen, a primary or secondary lower alkyl or a phenyl), and 0.01 to 10.0 parts by weight of (B) a modifier selected from **the group consisting of** conjugated non-aromatic diene compounds, dienophilic compounds having one dienophile group and precursors of the diene or dienophilic compounds, wherein the number of rearrangement structures each represented by the following formula (2):



(2)

(wherein R_1 , R_2 , R_3 and R_4 have the same meanings as defined above in the formula (1)) is less than 0.01 per 100 phenylene ether units of the formula (1).

7. (Amended) A process for preparing a modified polyphenylene ether resin, which comprises:

reacting a mixture of 100 parts by weight of (A) a polyphenylene ether having a main chain structure of the formula (1) and 0.01 to 10 parts by weight of (B) a modifier selected from the group consisting of conjugated non-aromatic diene compounds, dienophilic compounds having one dienophile group and precursors of the diene or dienophilic compounds at a temperature not lower than a room temperature and not higher than the melting point of (A).

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